(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
3 January 2008 (03.01.2008)

PCT

(10) International Publication Number
WO 2008/002944 A1

(51) International Patent Classification:
H01L 23/02 (2006.01) *H01L 21/52* (2006.01)

(21) International Application Number:
PCT/US2007/072164

(22) International Filing Date: 26 June 2007 (26.06.2007)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
11/479,633 29 June 2006 (29.06.2006) US

(71) Applicant *(for all designated States except US)*: **INTEL CORPORATION** [US/US]; 2200 Mission College Boulevard, Santa Clara, California 95052 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **OGATA, Kazuo** [JP/JP]; 2-8-7 Umezono, Tsukuba, Ibaraki 305-0045 (JP). **FUKUO, Tsuyoshi** [JP/JP]; 4-6-B204 Onogawa, Tsukuba, Ibaraki 305-0053 (JP). **ISHIYAMA, Seiji** [JP/JP]; 137-27-209 Tagi-cho, Ushiku, Ibaraki 300-1236 (JP). **KOH, Tetsuhide** [KR/JP]; 2-14-205 Senzoku, Tsuchiura, Ibaraki 300-046 (JP).

(74) Agents: **VINCENT, Lester, J.** et al.; Blakely, Sokoloff, Taylor & Zafman LLP, 1279 Oakmead Parkway, Sunnyvale, California 94085 (US).

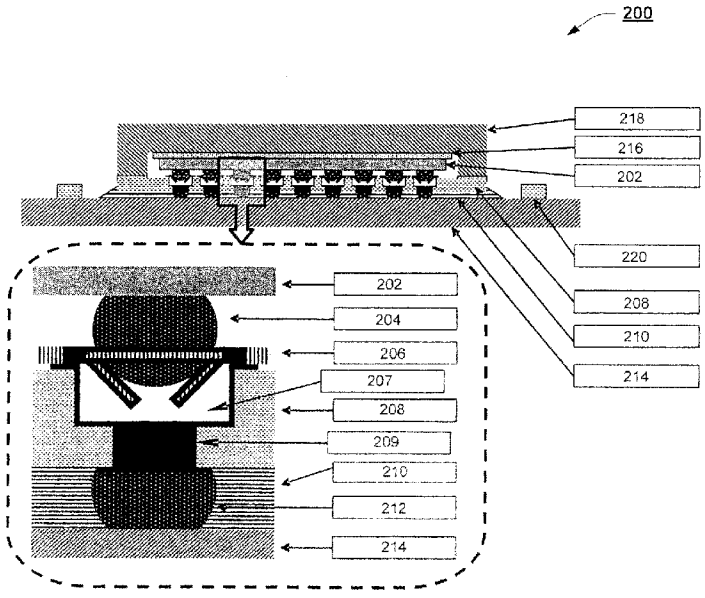
(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

[Continued on next page]

(54) **Title:** FLEXIBLE JOINT METHODOLOGY TO ATTACH A DIE ON AN ORGANIC SUBSTRATE



(57) **Abstract:** In some embodiments, flexible joint methodology to attach a die on an organic substrate is presented. In this regard, an integrated circuit chip package substrate is introduced having an organic substrate, an interposer coupled with a surface of the organic substrate, the interposer having cavities to accept bumps of a die, and a flexible tape layer coupled with a surface of the interposer, the flexible tape layer to couple with bumps of the die. Other embodiments are also disclosed and claimed.

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